

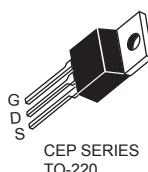
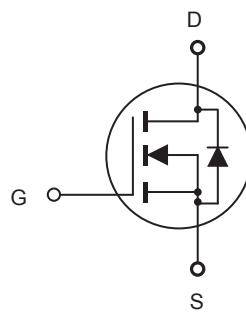


CEP6060L/CEB6060L

N-Channel Enhancement Mode Field Effect Transistor

FEATURES

- 60V, 50A, $R_{DS(ON)} = 20\text{m}\Omega$ @ $V_{GS} = 10\text{V}$.
 $R_{DS(ON)} = 25\text{m}\Omega$ @ $V_{GS} = 5\text{V}$.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handing capability.
- Lead free product is acquired.
- TO-220 & TO-263 package.

CEB SERIES
TO-263(DD-PAK)CEP SERIES
TO-220

ABSOLUTE MAXIMUM RATINGS

$T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 16	V
Drain Current-Continuous @ $T_C = 25^\circ\text{C}$ @ $T_C = 100^\circ\text{C}$	I_D	50 35	A
Drain Current-Pulsed ^a	I_{DM}	200	A
Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$ - Derate above 25°C	P_D	100 0.8	W W/ $^\circ\text{C}$
Operating and Store Temperature Range	T_J, T_{stg}	-65 to 175	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.5	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	$^\circ\text{C}/\text{W}$



CEP6060L/CEB6060L

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	60			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 60\text{V}, V_{\text{GS}} = 0\text{V}$			25	μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 16\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -16\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
On Characteristics^b						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	1	1.4	2	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 10\text{V}, I_D = 24\text{A}$		15	20	$\text{m}\Omega$
		$V_{\text{GS}} = 5\text{V}, I_D = 24\text{A}$		19	25	$\text{m}\Omega$
Dynamic Characteristics^c						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		1480		pF
Output Capacitance	C_{oss}			300		pF
Reverse Transfer Capacitance	C_{rss}			50		pF
Switching Characteristics^c						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 30\text{V}, I_D = 48\text{A}, V_{\text{GS}} = 5\text{V}, R_{\text{GEN}} = 15\Omega$		15	19.5	ns
Turn-On Rise Time	t_r			4.5	5.9	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$			124	161.2	ns
Turn-On Fall Time	t_f			22	28.6	ns
Total Gate Charge	Q_g	$V_{\text{DS}} = 48\text{V}, I_D = 48\text{A}, V_{\text{GS}} = 10\text{V}$		45	58.5	nC
Gate-Source Charge	Q_{gs}			4.6		nC
Gate-Drain Charge	Q_{gd}			9		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current	I_S				50	A
Drain-Source Diode Forward Voltage ^b	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = 50\text{A}$		0.8	1.3	V
Notes :						
a.Repetitive Rating : Pulse width limited by maximum junction temperature.						
b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.						
c.Guaranteed by design, not subject to production testing.						



CEP6060L/CEB6060L

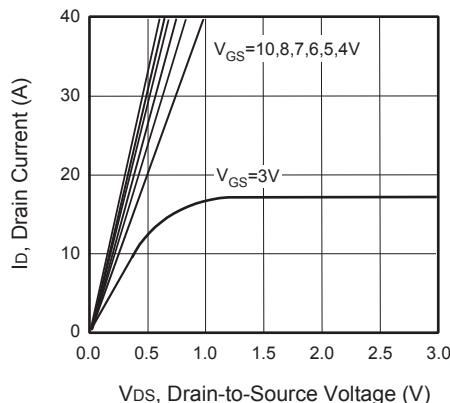


Figure 1. Output Characteristics

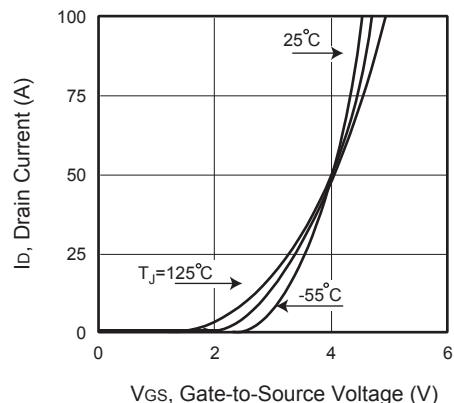


Figure 2. Transfer Characteristics

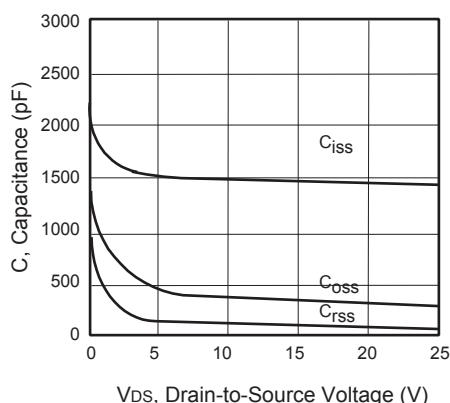


Figure 3. Capacitance

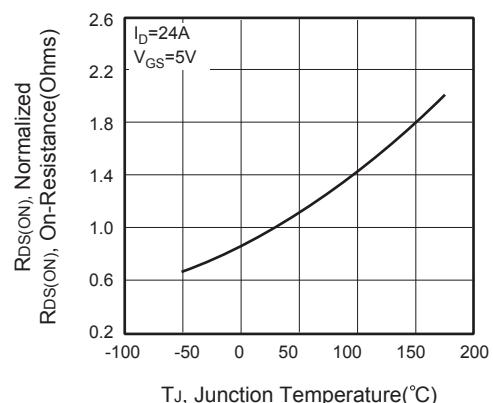


Figure 4. On-Resistance Variation with Temperature

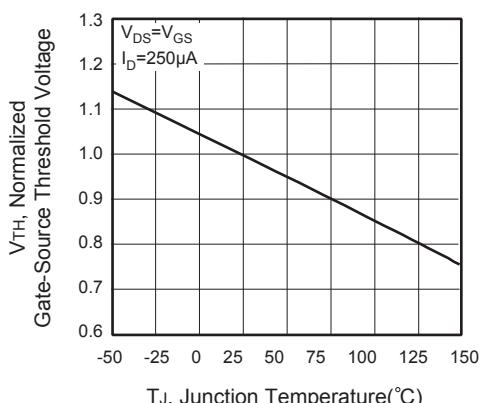


Figure 5. Gate Threshold Variation with Temperature

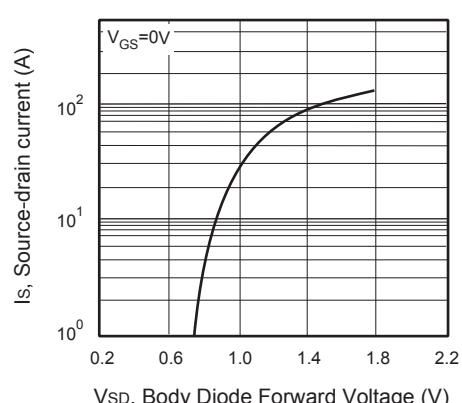


Figure 6. Body Diode Forward Voltage Variation with Source Current



CEP6060L/CEB6060L

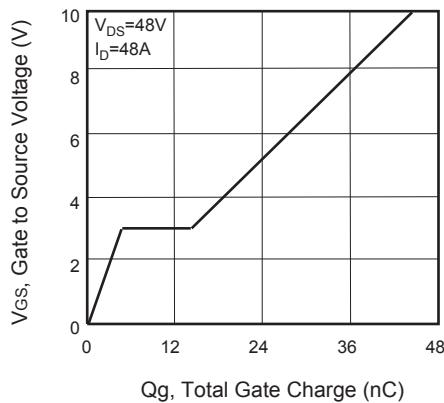


Figure 7. Gate Charge

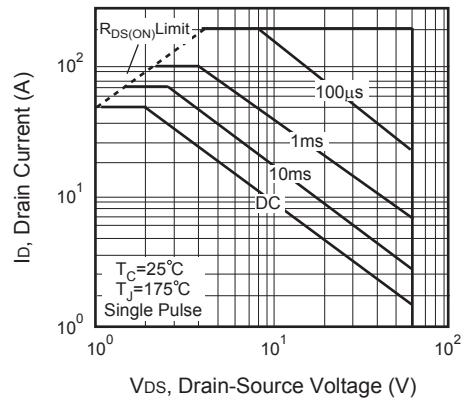


Figure 8. Maximum Safe Operating Area



Figure 9. Switching Test Circuit



Figure 10. Switching Waveforms

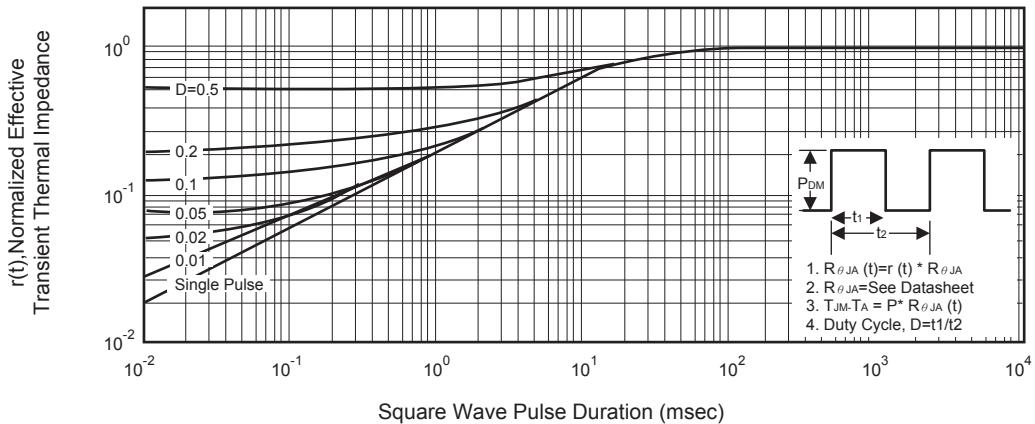


Figure 11. Normalized Thermal Transient Impedance Curve